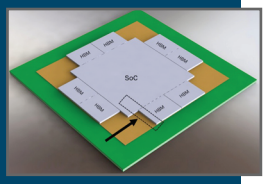
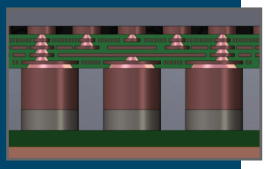
Advanced Packaging Update:
Market and Technology Trends

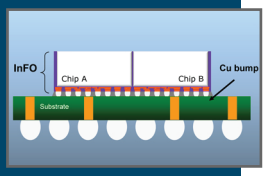
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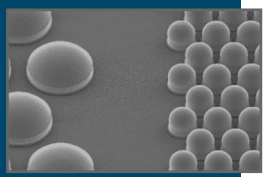












This issue of the Advanced Packaging Update features special coverage on the laminate substrate shortage with an analysis of the gap between FC-BGA supply and demand. Alternatives such as RDL interposers and fan-out WLP are discussed. An analysis of the importance of yield improvement is included. An update on 5G packages for smartphones and infrastructure is provided. The report examines the growth of electric vehicles. OSAT financials are presented. A special section on semiconductor shortages is included.

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